

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2735345

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>DONG YEAN OH</td> <td>01/22/2014</td> </tr> <tr> <td>KANG SIK CHOI</td> <td>01/22/2014</td> </tr> </tbody> </table>		Name	Execution Date	DONG YEAN OH	01/22/2014	KANG SIK CHOI	01/22/2014
Name	Execution Date						
DONG YEAN OH	01/22/2014						
KANG SIK CHOI	01/22/2014						
RECEIVING PARTY DATA							
Name:	SK HYNIX INC.						
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB, ICHEON-SI						
City:	GYEONGGI-DO						
State/Country:	KOREA, REPUBLIC OF						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14185495</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14185495		
Property Type	Number						
Application Number:	14185495						
CORRESPONDENCE DATA							
Fax Number:	(571)327-5452						
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>							
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Address Line 4:	VIENNA, VIRGINIA 22182						
ATTORNEY DOCKET NUMBER:	OPX13201-134US						
NAME OF SUBMITTER:	JUN JEONG PARK						
Signature:	/Jun Jeong PARK/						
Date:	02/20/2014						

This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

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source=OPX13201-134US_HWL_Assignment Declaration#page2.tif

ASSIGNMENT OF AND DECLARATION FOR APPLICATION
FOR UNITED STATES LETTERS PATENT

WHEREAS OH, Dong Yeon et al.,
hereinafter referred to collectively as the assignor and inventor, has invented a certain improvement relating to

VERTICAL-TYPE SEMICONDUCTOR APPARATUS AND FABRICATION METHOD THEREOF.

[X] said application being attached hereto;
[] said application having been filed in the United States Patent and Trademark Office on _____, as Application Serial No. _____, and was amended on _____ (if applicable);
[] the specification of which was filed under the Patent Cooperation Treaty on _____, Serial No. _____, the United States of America being designated.

AND WHEREAS SK hynix Inc.
hereinafter referred to as the assignee or applicant, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

As an above-named inventor, I hereby declare that the above-identified application was made or authorized to be made by me, and that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNOR (INVENTOR):

Signature: OH, DONG YEAN Date: Jan. 22. 2014

Printed or Typed Name: OH, Dong Yeon

ASSIGNMENT OF AND DECLARATION FOR APPLICATION FOR UNITED STATES LETTERS PATENT

Signature: CHOI, KANGSUK Date: Jan. 22, 2014

Printed or Typed Name: CHOI, Kang Sik

